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8-Bit Shift Register with Output Register

The MC74LV594A is an 8-bit shift register designed for 2 V to 6.0 V V_{CC} operation. The device contain an 8-bit serial-in, parallel-out shift register that feeds an 8-bit D-type storage register. Separate clocks (RCLK, SRCLK) and direct overriding clear (RCLR, SRCLR) inputs are provided on the shift and storage registers. A serial output ($Q_{H^{-}}$) is provided for cascading purposes.

The shift-register (SRCLK) and storage-register (RCLK) clocks are positive-edge triggered. If the clocks are tied together, the shift register always is one clock pulse ahead of the storage register.

Features

- 2.0 V to 6.0 V V_{CC} Operation
- Low Input Current: 1.0 μA
- Max t_{pd} of 6.5 ns at 5 V
- Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 3.3 V, T_A = 25° C
- Typical V_{OHV} (Output V_{OH} Undershoot) > 2.3 V at V_{CC} = 3.3 V, T_A = 25°C
- Support Mixed-Mode Voltage Operation on All Ports
- 8-Bit Serial-In, Parallel-Out Shift Registers With Storage
- Independent Direct Overriding Clears on Shift and Storage Registers
- Independent Clocks for Shift and Storage Registers
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance with the Requirements Defined by JEDEC Standard No. 7A
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant



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ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

FUNCTION TABLE

		INPUTS			FUNCTION
SER	S RCLK	SRCLR	RCLK	RCLR	FUNCTION
Х	Х	L	Х	Х	Shift register is cleared.
L	Ŷ	н	х	х	First stage of shift register goes low. Other stages store the data of previous stage, respectively.
н	Ŷ	н	х	х	First stage of shift register goes high. Other stages store the data of previous stage, respectively.
L	Ļ	Н	Х	Х	Shift register state is not changed.
х	Х	Х	Х	L	Storage register is cleared.
Х	Х	Х	Ŷ	н	Shift register data is stored in the storage register.
х	х	х	\downarrow	н	Storage register state is not changed.



Figure 1. Logic Diagram





ORDERING INFORMATION

Device	Package	Shipping [†]
MC74LV594ADR2G	SOIC-16 (Pb-Free)	2500 / Tape & Reel
MC74LV594ADTR2G	TSSOP-16 (Pb-Free)	2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{CC}	DC Supply Voltage	-0.5 to +7.0	V
VI	DC Input Voltage	–0.5 to V _{CC} + 0.5	V
V _O	DC Output Voltage Active Mode (Note 1)	–0.5 to V _{CC} + 0.5	V
	High Impedance or Power-Off Mode	-0.5 to +7.0	
I _{IK}	DC Input Clamp Current	±20	mA
I _{OK}	DC Output Clamp Current	±35	mA
I _{IN}	DC Input Current	±20	mA
Ι _Ο	DC Output Source / Sink Current	±35	mA
I _{CC}	DC Supply Current per Supply Pin	±75	mA
I _{GND}	DC Ground Current per Ground Pin	±75	mA
T _{STG}	Storage Temperature Range	-65 to +150	°C
ΤL	Lead temperature, 1 mm from Case for 10 Seconds	260	°C
ТJ	Junction temperature under Bias	+150	°C
θ_{JA}	Thermal Resistance SOIC TSSOP	112 148	°C
P _D	Power Dissipation in Still Air at SOIC TSSOP	500 450	mW
MSL	Moisture Sensitivity	Level 1	
F _R	Flammability Rating Oxygen Index: 30% – 35%	UL–94–VO (0.125 in)	
V _{ESD}	ESD Withstand Voltage Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)	> 3000 >400 N/A	V
I _{Latchup}	Latchup Performance Above V_{CC} and Below GND at 85°C (Note 5)	±300	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality Stresses exceeding those listed in the Maximum Hatings table may damage to should not be assumed, damage may occur and reliability may be affected.
1. I_O absolute maximum rating must be observed.
2. Tested to EIA/JESD22-A114-A.
3. Tested to EIA/JESD22-A115-A.
4. Tested to JESD22-C101-A.
5. Tested to FIA/JESD22.

5. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS (Note 6)

Symbol	Parameter	Min	Max	Unit
V _{CC}	DC Supply Voltage (Referenced to GND)	2.0	6.0	V
VI	DC Input Voltage (Referenced to GND)	0	V _{CC}	V
V _O	DC Output Voltage (Referenced to GND)	0	V _{CC}	V
T _A	Operating Free–Air Temperature	-55	+125	°C
t _r , t _f	Input Rise or Fall Rate $V_{CC} = 2.0 \text{ V}$ $V_{CC} = 4.5 \text{ V}$ $V_{CC} = 6.0 \text{ V}$	0 0 0	1000 500 400	nS

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

6. All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.

DC ELECTRICAL CHARACTERISTICS

					C	Guaranteed L	imits		
				٦	A = 25°C	;	T _A = -55°	C to 125°C	
Symbol	Parameter	Conditions	V _{CC} , (V)	Min	Тур	Max	Min	Max	Unit
M	Minimum		2.0	1.5			1.5		V
VIH	put Voltage		2.3 - 6.0	0.7 x V _{CC}			0.7 x V _{CC}		V
N/	Maximum		2.0			0.5		0.5	N
VIL	put Voltage		2.3 - 6.0			0.3 x V _{CC}		$0.3 \times V_{CC}$	V
		$V_{IN} = V_{IH} \text{ or } V_{IL}$							
	Minimum	I _{oH} = -50 μA	2.0 - 6.0	V _{CC} - 0.1			V _{CC} – 0.1		V
V _{OH} Hig Ou	High-Level Output Voltage	$I_{OH} = -2 \text{ mA}$	2.3	2			2		
	1 0	I _{oH} = -6 mA	3.0	2.48			2.48		
		$I_{oH} = -12 \text{ mA}$	4.5	3.8			3.8		
		$V_{IN} = V_{IH} \text{ or } V_{IL}$							
	Maximum	l _{oH} = 50 μA	2.0 - 6.0			0.1		0.1	
V _{OL}	Low-Level	I _{oH} = 2 mA	2.3			0.4		0.4	V
	Oulput vollage	I _{oH} = 6 mA	3.0			0.44		0.44	
		l _{oH} = 12 mA	4.5			0.55		0.55	
I _{IN}	Maximum In- put Leakage Current	V _I = V _{CC} or GND	6.0		±0.1		±1		μΑ
Icc	Maximum Sup- ply Current	$V_{I} = V_{CC} \text{ or}$ GND, $I_{O} = 0 \text{ A}$	6.0			8.0		80	μΑ
CI	Input Capacit- ance	V _I = V _{CC} or GND	3.3		3.5				pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TIMING SPECIFICATIONS (See Figure 3)

				T _A =	25°C	T _A = -55°C	C to 125°C	
Symbol	Parameter	Conditions	V_{CC} , (V)	Min	Max	Min	Max	Unit
tw	Pulse Duration	RCLK or SRCLK	2.3 – 2.7	7		7.5		ns
		High or Low	3.0 - 3.6	5.5		5.5		
			4.5 - 5.5	5		5		
		RCLR or SRCLR Low	2.3 – 2.7	6		6.5		
			3.0 - 3.6	5		5		
			4.5 – 5.5	5.2		5.2		
			2.3 – 2.7	5.5		5.5		
		SER before SRCLK↑	3.0 - 3.6	3.5		3.5		
			4.5 - 5.5	3		3		
		SRCLK↑ before RCLK↑	2.3 – 2.7	8		9		
			3.0 - 3.6	8		8.5		
			4.5 - 5.5	5		5		
		SRCLR Low before RCLK1	2.3 – 2.7	8.5		9.5		
t _{SU}	Setup Time		3.0 - 3.6	8		9		ns
			4.5 - 5.5	5		5		
		SRCLR High (Inactive)	2.3 – 2.7	6		6.8		
		SRCLK1	3.0 - 3.6	4.2		4.8		
			4.5 - 5.5	2.9		3.3		
		RCLR High (Inactive)	2.3 – 2.7	6.7		7.6		
		Defore RGLK	3.0 - 3.6	4.6		5.3		
			4.5 - 5.5	3.2		3.7		
			2.3 – 2.7	1.5		1.5		
t _H	Hold Time	SER after SRCLK [↑]	3.0 - 3.6	1.5		1.5		ns
			4.5 - 5.5	2		2		

AC CHARACTERISTICS (See Figure 3)

						Guai	anteed Li	mits		
		Load Condi-				T _A = 25°C		T _A = -5 125	55°C to 5°C	
Symbol	Paraeter	tions	Input to Output	V_{CC} , (V)	Min	Тур	Мах	Min	Max	Unit
				2.3 – 2.7	65	80		45		
		C _L = 15 pF		3.0 - 3.6	80	120		70		
funy				4.5 – 5.5	135	170		115		MH-7
IMAX				2.3 – 2.7	50	51		40		
		$C_L = 50 \text{ pF}$		3.0 - 3.6	70	74		55		
				4.5 – 5.5	115	120		90		
		0 15 -5	RCLK to Q _A -Q _H	2.3 – 2.7			27.5	1	32.5	-
				3.0 - 3.6			18	1	22.5	
				4.5 – 5.5			12	1	15	
		0L = 13 pi		2.3 – 2.7			27.5	1	32	
			SRCLK to Q _{H'}	3.0 - 3.6			18	1	22	
t	Propagation			4.5 – 5.5			12.5	1	12	20
ⁱ PLH	High		DOLIC	2.3 – 2.7		22.1	25.0	1	30.0	115
			RCLK to Q _A -Q _H	3.0 - 3.6		15.6	17.5	1	21.0	1
		$C_{1} = 50 \text{ pF}$		4.5 – 5.5		11.5	12.5	1	15.5	
		0L = 30 hF		2.3 – 2.7		21.6	25.5	1	29.5	
			SRCLK to Q _{H'}	3.0 - 3.6		15.2	18.0	1	21.0	
				4.5 - 5.5		10.9	12.5	1	15.0	

AC CHARACTERISTICS (See Figure 3)

						Gua	anteed Li	mits		
		Load Condi-				T _A = 25°C		T _A = -{ 12	55°C to 5°C	
Symbol	Paraeter	tions	Input to Output	V _{CC} , (V)	Min	Тур	Max	Min	Max	Unit
				2.3 – 2.7			23	1	27.5	
			RCLK to Q _A –Q _H	3.0 - 3.6			15.5	1	19	
			7411	4.5 – 5.5			11	1	14	
				2.3 – 2.7			23.5	1	27	
			SRCLK to QH'	3.0 - 3.6			16	1	19	
		0 15 55		4.5 – 5.5			11	1	13.5	
		0L = 15 pF		2.3 – 2.7			20.5	1	25	
			RCLR to Q _A -Q _H	3.0 - 3.6			14.5	1	17.5	
				4.5 – 5.5			10	1	12	
			SRCLR to Q _{H'}	2.3 – 2.7				1	23	
				3.0 - 3.6			13	1	16	
	Propagation			4.5 – 5.5			9	1	11	
^I PHL	Low			2.3 – 2.7		19.7	23.0	1	27.0	ns
			RCLK to Q₄–Q _H	3.0 - 3.6		14.0	16.5	1	19.5	
				4.5 – 5.5		10.1	11.5	1	13.5	
				2.3 – 2.7		18.4	21.5	1	25.0	
			SRCLK to Q _{H'}	3.0 - 3.6		13.1	15.0	1	18.0	
		0 50 - 5		4.5 – 5.5		9.0	10.5	1	12.5	
		CL = 50 pF		2.3 – 2.7		25.7	30.0	1	35.0	
			RCLR to Qa-QH	3.0 - 3.6		17.6	20.0	1	24.5	
				4.5 – 5.5		12.2	13.5	1	17.0	
				2.3 – 2.7		25.3	30.0	1	34	
			SRCLR to Q _{H'}	3.0 - 3.6		17.3	20.0	1	24.0	
				4.5 – 5.5		11.9	14.0	1	16.5	

NOISE CHARACTERISTICS, V_{CC} = 3.3 V, C_L = 50 pF, T_A = 25°C

Symbol	Parameter	Min	Тур	Max	Unit
V _{OL(P)}	Quiet Output, Maximum Dynamic V _{OL}		0.8	0.8	V
V _{OL(V)}	Quiet Output, Minimum Dynamic V _{OL}		-0.1	-0.8	V
V _{OH(V)}	Quiet Output, Minimum Dynamic V _{OH}		2.8		V
V _{IH(D)}	High-Level Dynamic Input Voltage	2.31			V
V _{IL(D)}	Low-Level Dynamic Input Voltage			0.99	V

POWER DISSIPATION CHARACTERISTICS, T_{A} = $25^{\circ}C$

Symbol	Parameter	Test Conditions	V _{CC} (V)	Тур	Unit
C _{PD}	Power Dissipation Capacitance	f = 10 MHz	3.3	93	pF
			5	112	

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. CL includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f \leq 3 ns, t_f \leq 3 ns.
 - D. The outputs are measured one at a time, with one input transition per measurement.
 - E. tPLZ and tPHZ are the same as tdis.
 - F. tpzL and tpzH are the same as ten.
 - G. t_{PHL} and t_{PLH} are the same as t_{pd}.
 - H. All parameters and waveforms are not applicable to all devices.

Figure 3. Load Circuit and Voltage Waveforms

PACKAGE DIMENSIONS

MIN MAX

0.007 0.011

0.004 0.008

0.252 BSC

8

0

8

0.047



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS



NOTES:

DIMENSIONING AND TOLERANCING PER ANSI

VI4.5M, 1982. CONTROLLING DIMENSION: MILLIMETER. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION

MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION 5.

SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	9.80	10.00	0.386	0.393
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050	BSC
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0 °	7°	0 °	7°
Р	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

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